❑ MN1874086

Type			**MN1874086**
ROM (×8-Bit)			40 K
RAM (×8-Bit)			640
Minimum Instruction Execution Time			**0.5 µs at 2/3 frequency dividing (at 4.5 V to 5.5 V, 12 MHz)**
Interrupts			• RESET • External 0 • External 1 • Timer 0 • Timer 1 • Timer 2 • I²C • Remote Control • Line 21 • COSD
Timer Counter			**Timer Counter 0 : 8-Bit × 1** Clock Source 1/1, 1/4, 1/16, 1/64 of System Clock Interrupt Source Overflow of Timer Counter 0 **Timer Counter 1 : 8-Bit × 1** Clock Source 1/2, 1/16, 1/64, 1/256, 1/512 of System Clock Interrupt Source Overflow of Timer Counter 1 **Time Base Counter** Clock Source 1/4096 of System Clock Interrupt Source 1/1, 1/2, 1/4, 1/8 of Timer Counter 2 **Watchdog**
Serial Interface			**I²C × 1** (Two bus line system)
I/O Pins	**I/O**	**21**	• Common use 5
	Input	**1**	• Common use 1
	Output	**7**	• Nch Open-Drain 7
A/D Inputs			5-Bit × 7ch (without S/H)
PWM			14-Bit × 1ch (Repetition Cycle 16 µs, at 12 MHz), 8-Bit × 8ch (Repetition Cycle 32 µs, at 12 MHz), 7-Bit × 1ch (Repetition Cycle 16 µs, at 12 MHz) (All PWM are 5 V , not connectable to 12 V systems)
Special Ports			Remote Control Reception
CRTC			Single OSD built-in (Caption OSD 12 × 26 dots 256 letters)
Notes			Remote Control Data Detection Circuit built-in, On-Chip synchronous separator for caption decoder, ROM Correction Circuit built-in
Package			SDIP064-P-0750

Electrical Characteristics

A/D Converter Characteristics

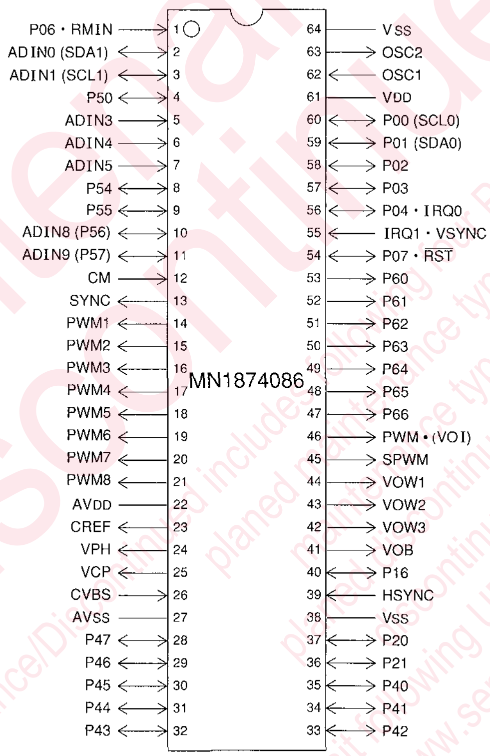
Parameter	Symbol	Condition	Limit min	Limit typ	Limit max	Unit
A/D Conversion Time	TAD	fosc = 12 MHz	9			µs
Analog Input Voltage	VAD		VSS		VDD	V

(Ta = –20 °C to +70 °C, VDD = 5.0 V, VSS = 0 V)

Support Tool

In-Circuit Emulator	PX-ICE1870 / 80 + PX-PRB1879682	
EPROM built-in Type	**Type**	MN18P79682
	ROM (× 8-Bit)	96 K
	RAM (× 8-Bit)	1 248
	Minimum Instruction Execution Time	0 333 µs (at 4 5 V to 5 5 V, 12 MHz)
	Package	SDIP064-P-0750

Pin Assignment



SDIP064-P-0750

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